imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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SPECIFICATION

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL21A475KOFNNNG

(Reference sheet)

- · Description :
- CAP, 4.7uF, 16V, ±10%, X5R, 0805

A. Samsung Part Number

			<u>CL</u> ①	<mark>21</mark> ②	<mark>≜</mark> ₃	<u>475</u> ④	<u>K</u> 5	<mark>0</mark> 6	<u>Е</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>G</mark> (11)	
1	Series	Samsung M	/lulti-la	ayer (Cerar	nic Ca	oacito	or						
2	Size	0805 (in	ch co	ode)		L:	2.00	± 0.10	mm			W:	1.25 ± 0.10	mm
3	Dielectric	X5R					8	Inner	elect	rode			Ni	
4	Capacitance	4.7 uF						Term	inatio	n			Cu	
5	Capacitance	±10 %						Platir	ıg				Sn 100%	(Pb Free)
	tolerance						9	Prod	uct				Normal	
6	Rated Voltage	16 V					10	Spec	ial				Reserved fo	r future use
1	Thickness	1.25 ± 0.10	mm				1	Pack	aging				Embossed T	Type, 7" reel

B. Structure & Dimension



Samsung P/N	Dimension(mm)								
Samsung F/N	L	W	Т	BW					
CL21A475KOFNNNG	2.00 ± 0.10	1.25 ± 0.10	1.25 ± 0.10	0.50 +0.20/-0.30					

C. Samsung Reliablility Test and Judgement Condition

Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	1 ^{kHz} ±10% / 1.0±0.2Vrms *A capacitor prior to measuring the capacitance is heat treated at 150 °C +0/-10 °C for 1 hour and maintained in ambient air for 24±2 hours. Rated Voltage 60~120 sec.
Insulation10,000Mohm or 100Mohm×/#ResistanceWhichever is smallerAppearanceNo abnormal exterior appearanceWithstandingNo dielectric breakdown orVoltagemechanical breakdownTemperatureX5RCharacteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	treated at 150° C +0/-10 $^\circ$ C for 1 hour and maintained in ambient air for 24±2 hours.
ResistanceWhichever is smallerAppearanceNo abnormal exterior appearanceWithstandingNo dielectric breakdown orWithstandingNo dielectric breakdown orVoltagemechanical breakdownTemperatureX5RCharacteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	Rated Voltage 60~120 sec.
AppearanceNo abnormal exterior appearanceWithstandingNo dielectric breakdown orVoltagemechanical breakdownTemperatureX5RCharacteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	
WithstandingNo dielectric breakdown or mechanical breakdownVoltagemechanical breakdownTemperatureX5RCharacteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	
Voltagemechanical breakdownTemperatureX5RCharacteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	ce Microscope (×10)
Temperature X5R Characteristics (From-55 °C to 85 °C, Capacitance Adhesive Strength No peeling shall be occur on the terminal electrode Bending Strength Capacitance change : withi Solderability More than 75% of terminal surface is to be soldered newly	250% of the rated voltage
Characteristics(From-55 °C to 85 °C, CapacitanceAdhesive StrengthNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	
Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surface is to be soldered newly	
of Terminationterminal electrodeBending StrengthCapacitance change : withiSolderabilityMore than 75% of terminal surfaceis to be soldered newly	ce change should be within ±15%)
Bending Strength Capacitance change : withi Solderability More than 75% of terminal surface is to be soldered newly	e 500g·f, for 10±1 sec.
Solderability More than 75% of terminal surfa	
is to be soldered newly	in ±12.5% Bending to the limit (1mm)
is to be soldered newly	with 1.0mm/sec.
	ace SnAg3.0Cu0.5 solder
	245±5°C, 3±0.3sec.
	(preheating : 80~120℃ for 10~30sec.)
Resistance to Capacitance change : withi	in ±7.5% Solder pot : 270±5℃, 10±1sec.
Soldering Heat Tan δ, IR : initial spec.	
Vibration Test Capacitance change : withi Tan δ, IR : initial spec.	in ± 5% Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)
Moisture Capacitance change : withi	in ±12.5% With rated voltage
Resistance Tan δ : 0.125 max	40±2°C, 90~95%RH, 500+12/-0hrs
IR: 500Mohm or 12.5Mohr	m × μF
Whichever is smaller	
High Temperature Capacitance change : withi	in ±12.5% With 150% of the rated voltage
Resistance Tan δ : 0.125 max	Max. operating temperature
IR : 1,000Mohm or 25Mohr	m × ⊭F 1000+48/-0hrs
Whichever is smaller	
Temperature Capacitance change : withi	in ±7.5% 1 cycle condition
Cycling Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25°C
	\rightarrow Max. operating temperature \rightarrow 25°C
	→ Max. operating temperature → 25° C

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- ④ Military equipment
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.